

Preparation of next beam tests: *setting up the test benches at LAL*

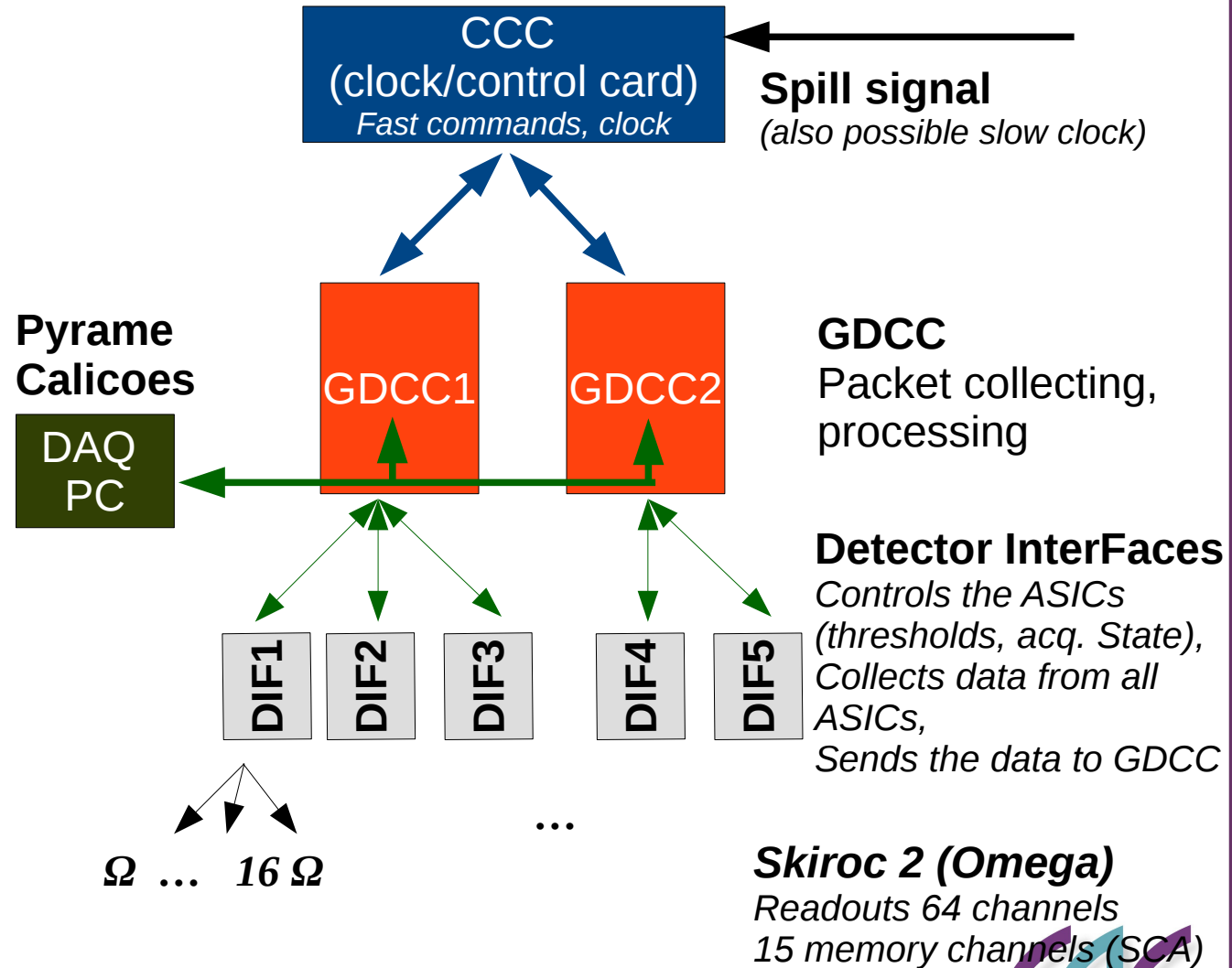
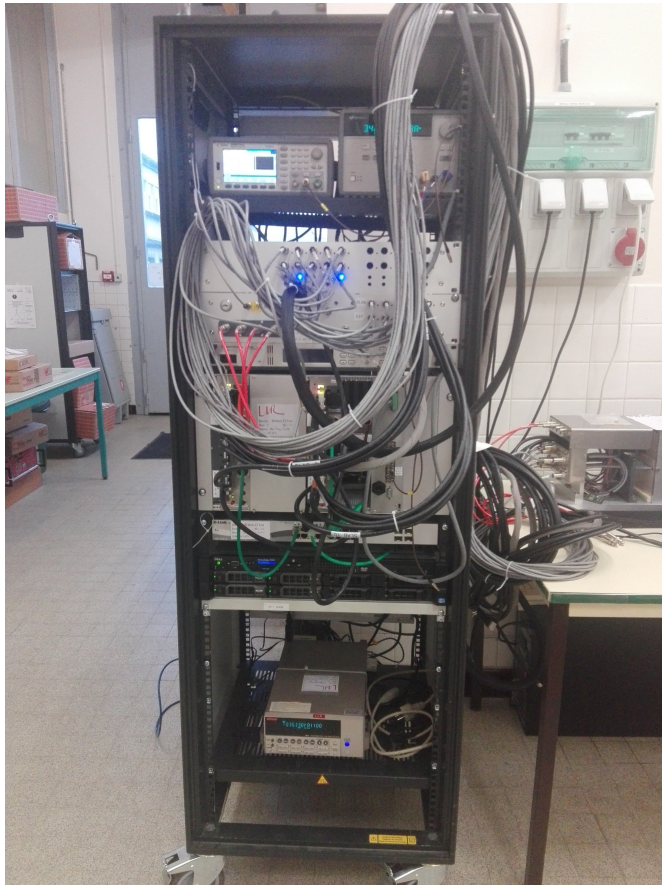
SiW-ECAL meeting

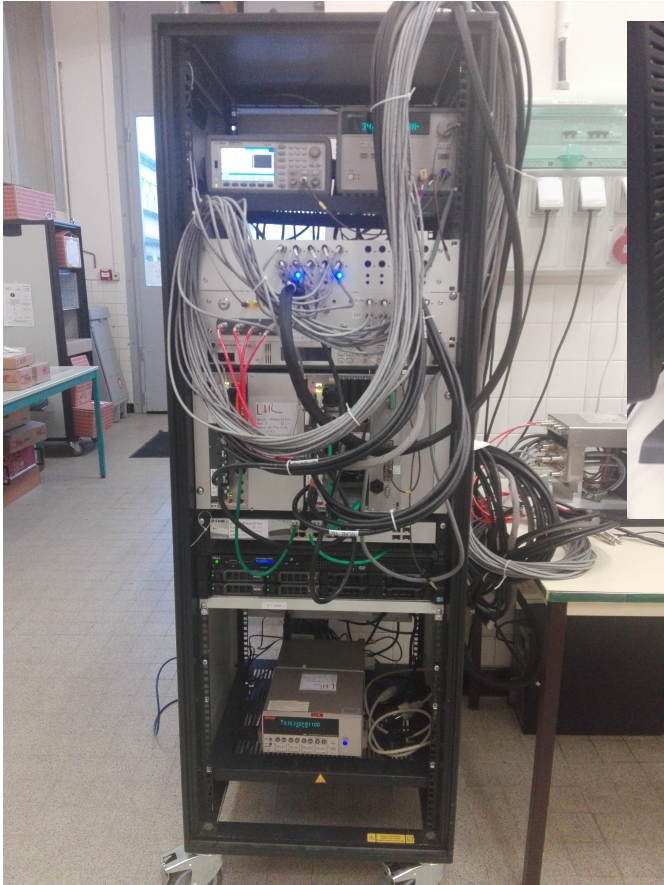
A. Irlès, Orsay 21st Mars 2017



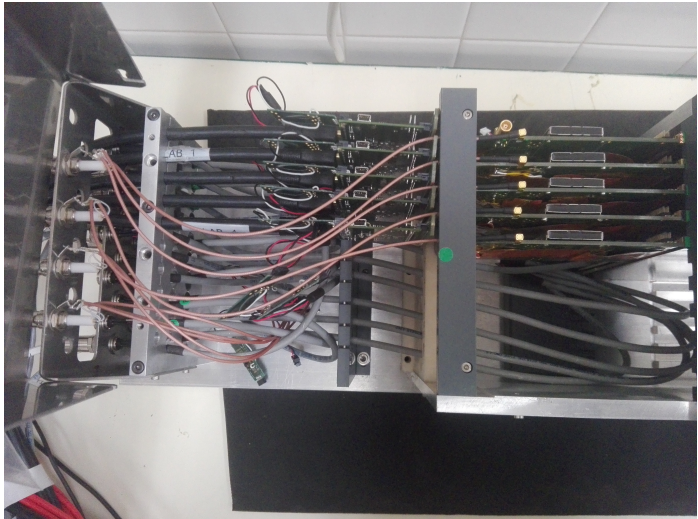
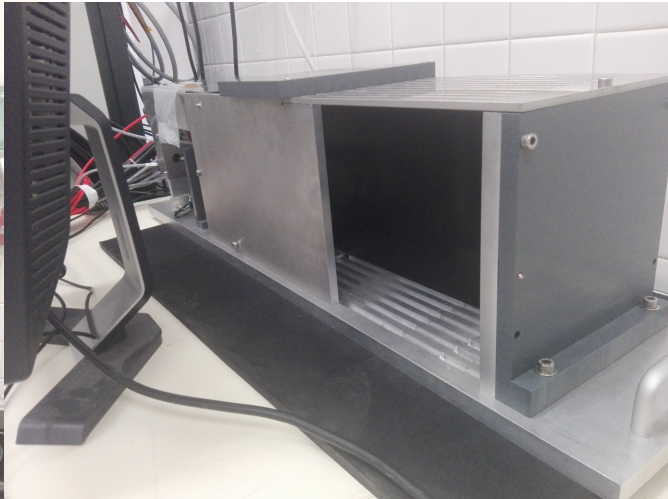
- LAL testbenches
 - Prototype (with LLR electronics and power rack)
 - Small testbench, currently with FEV8_cob (see next talk)
- Software roadplan: data quality
- Hardware roadplan (with beam test on the scope)
- Preliminary results with the prototype
 - Scurves
 - BCID issues
- Beam test:
 - Preparation
 - Schedule and organization.

DAQ & electronic setup schematics

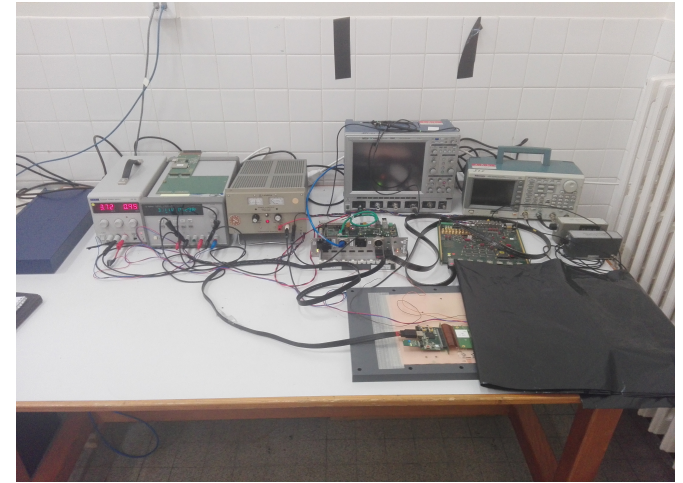
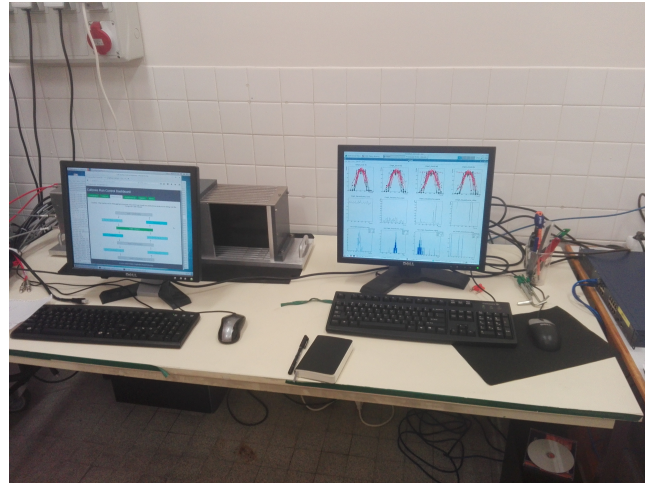




LLR rack with all servers and electronics -->plug and play



Prototype equipped with **5 FEV10 modules** with **16 chips (skiroc 2)**, 64 chn each = 5120 chn.



■ Two testbenches together (from left to right)

- Electronic rack for the prototype
- Control PC of the proto
- Prototype itself (5120 calorimeter cells behind a 15" screen)
- Monitoring PC (used for both testbenches)
- Testbench of single modules (FEV8)

■ Weeks of work together with engineers from LAL, LLR and OMEGA



- Set up the LAL rack
 - Power supplies, DAQ electronics, networking, etc
 - Didier Jehanno (Super KEKb) in close collaboration Remi Cornat
- Carefully test the new DAQ software and the prototype performance
 - First results already coming (we had already some very fruitful meetings at LAL and LLR)
 - **Workgroup created and progressing.**
- Hands on with Huisu Kim and Bokyeom Kim from Korea
 - See next talk.

- Sk2a replacing SK2 (see Artur's talk)
 - New set of CCC from Mainz to replace the old ones.
 - FEV12 and new wafers production/commisioning/integration
-
- All these items are ordered or under test/preparation → available after June testbeam
 - Not covered in this talk.

- I will work together with Frederic in the implementation of the online monitoring within CALICOES (DQM4HEP ?)
 - The facility is already there → work done during last test beam preparation.
 - Need small additions, testing and the development of the analysis methods.

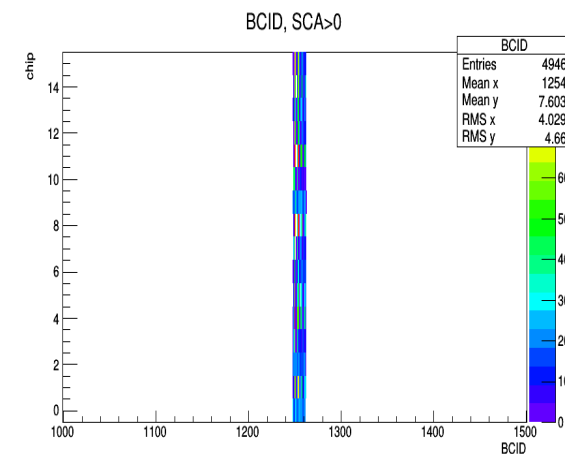
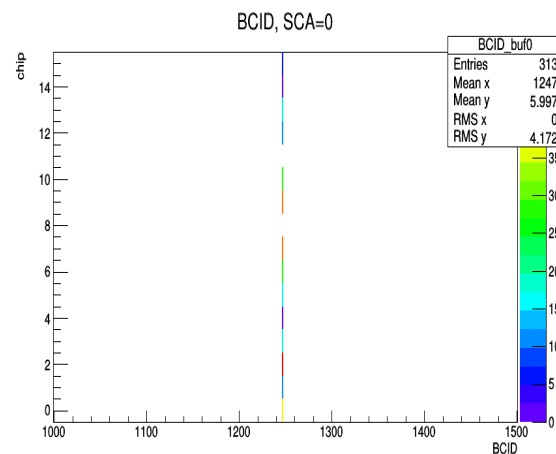
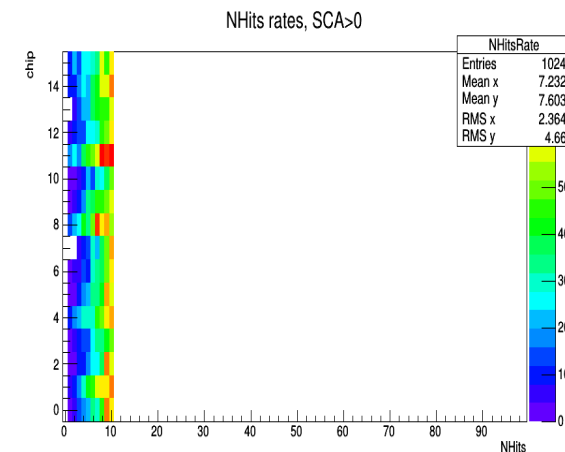
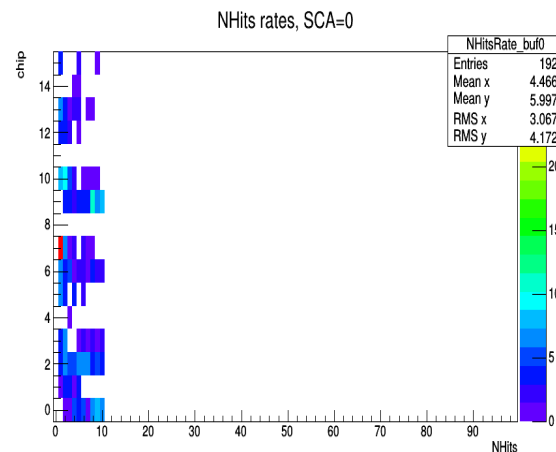
- For the moment we have a semionline Data Quality analysis framework that fulfills two functions:
 - Quick monitoring (chip and channel modules)
 - Quick analysis module manager: scurves, pedestal (ADC) extraction, MIP fit with pedestal subtraction, etc.
- It is under development: temporary repository <https://github.com/airqui/tpecal/>
- Uses root files as input. Nothing else is needed (calicoes, pyrame, etc).
 - Scriptable and exportable.
 - Feedback from V. Balagura (monitoring tool written in R)

■ Data taken at LAL with the prototype.

- Noise run, with low fast shaper threshold value (DAC = 190)
- FEV10, SK2.
- HV = on

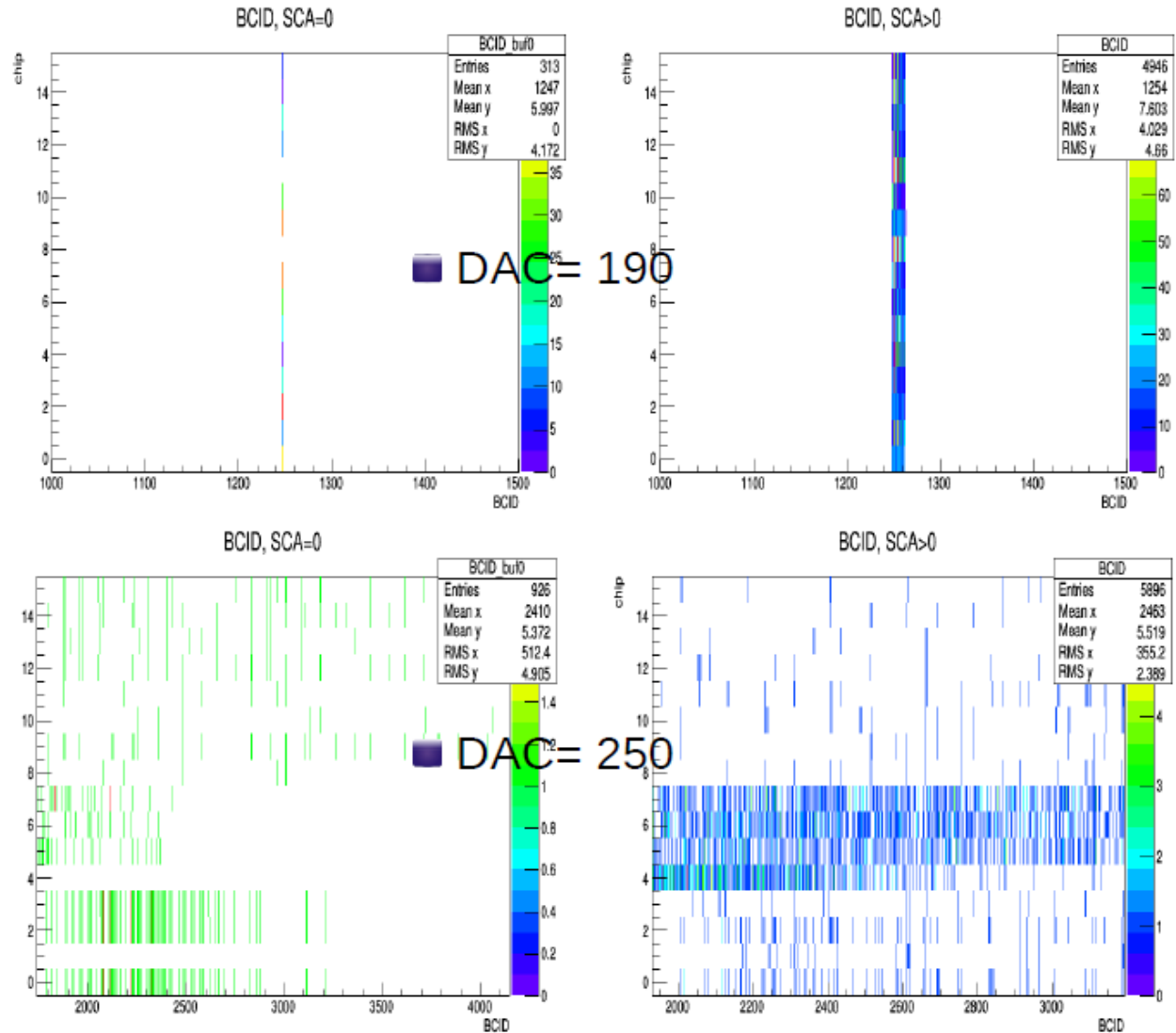
■ Plots for one ASIC

- Nhits (SCA=0 and SCA>0)
- BCID (SCA=0 and SCA>0). As the threshold is quite low, the BCIDs are ~ val_evt BCID.

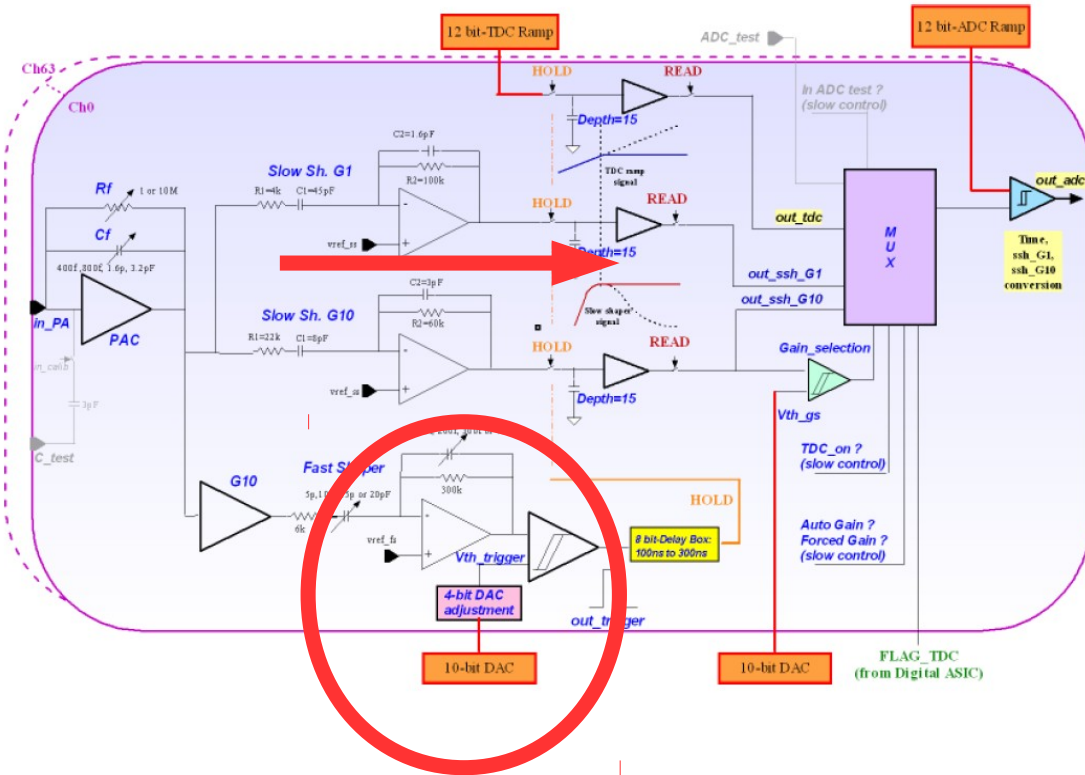


Preliminary results (I): Data Quality plots

- Comparison of same plots for low and high threshold values.
- Some features are observed in the BCID values:
 - Repetitive patterns for group of chips that trigger all at the same time.
 - First tests with HV off make the patterns disappear.
 - BCID values larger than spill (in principle, maximum BCID should be 2500 in these runs) → **under investigation**.

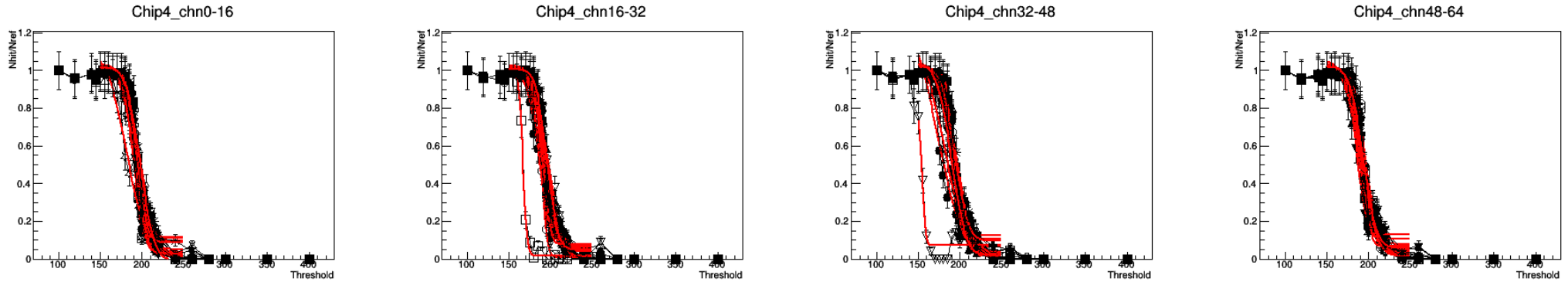


Preliminary results (II): noise threshold scans or scurves



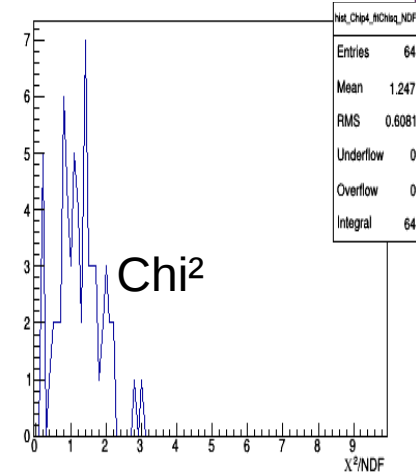
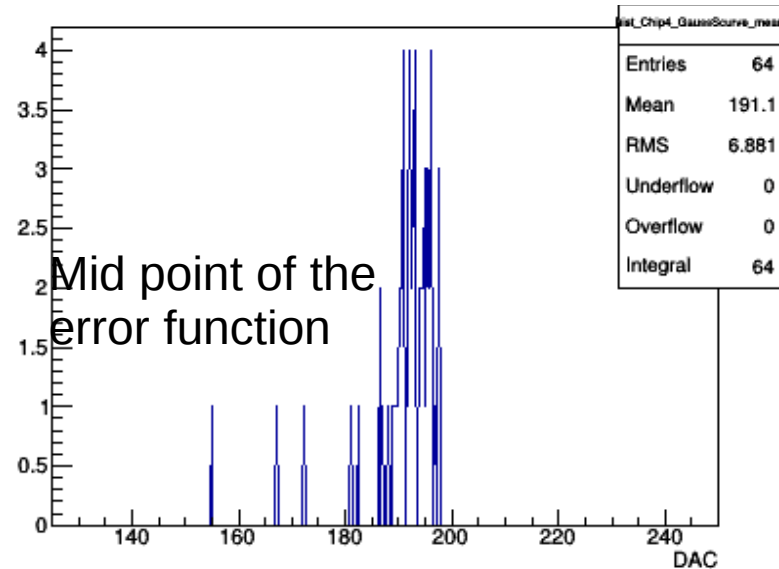
- Establish the pedestal of the fast shaper threshold (DAC)
- Scurves with DAQ
 - Make a scan varying the threshold values.
 - Count number of hits per channel (hit bit == 1)
 - Count SCA = 0 or all (two different approaches with similar results)
- Data taken for all 5 DIFs

Preliminary results (I): noise threshold scans or scurves

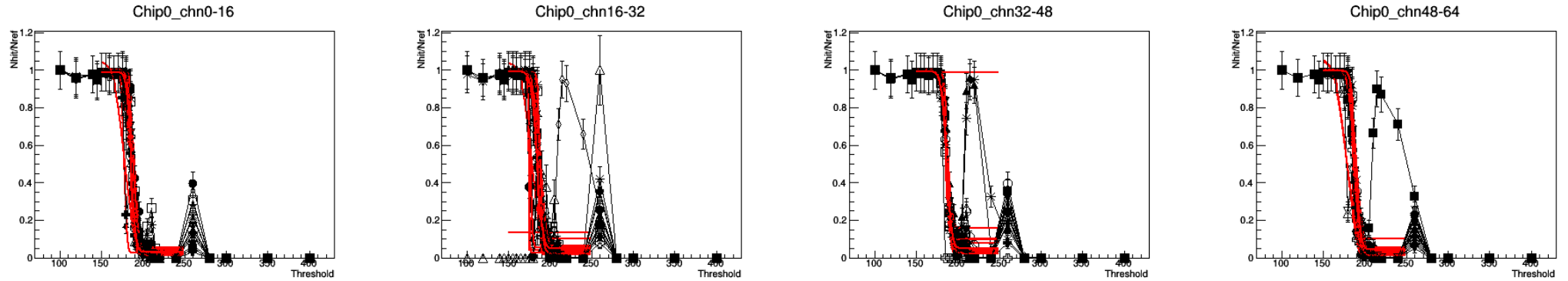


■ DIF 1, chip 4 (representative result)

- All channels enabled at the same time.
- High gain preamp.
- Threshold value (DAC) scan.
- Plot hits vs DAC for SCA = 0
- Fit 1-error_func to data
 - Threshold mean = 191.1 ± 6.8 DAC



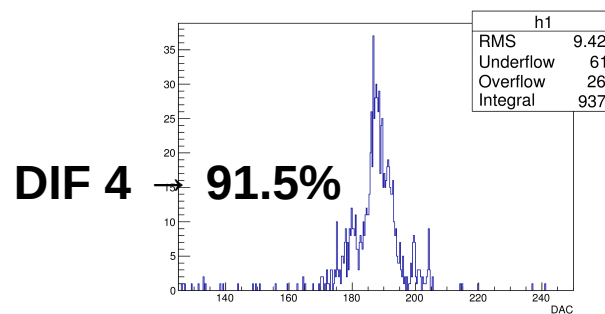
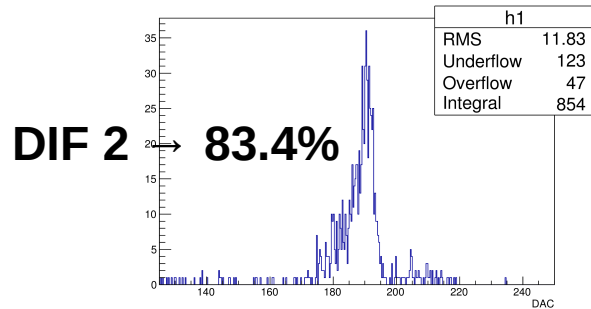
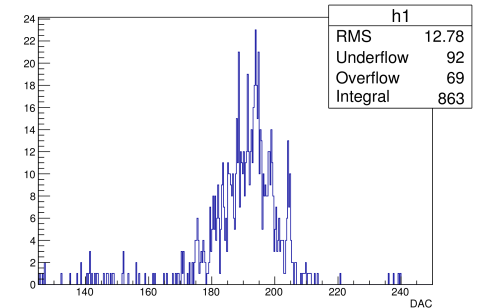
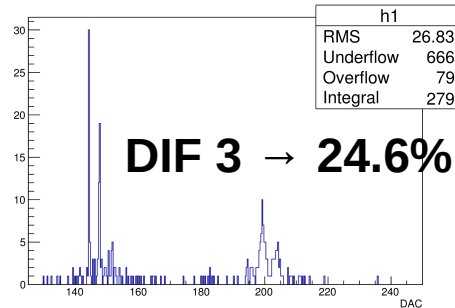
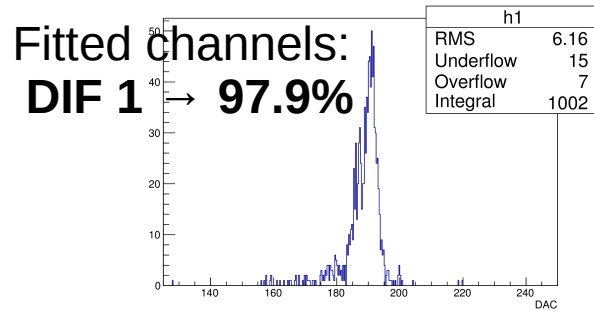
Preliminary results (I): noise threshold scans or scurves



- Chip 0, same DIF.
- Noise ?
- Observed in other chips → more detailed studies needed

Preliminary results (II): noise threshold scans or scurves

■ Summary plots of optimal threshold fit for all DIFs



■ Preliminary results not optimized analysis or results checked carefully but ... **promising.**

- **Still preliminary and non conclusive results but...**
- **The tests and debugging has now really started at many fronts.**
 - I will focus on the prototype and DQM
 - Artur & Shridha, sk2a and various testbenches at LLR.

- **We have started a weekly meeting (“TB2017 task force”)**
 - Frequency to be reduced eventually → we are creating the momentum!
 - Agenda Linear Collider (is this the right place for such kind of very technical meetings?)
 - <https://agenda.linearcollider.org/category/155/>

■ Roadplan:

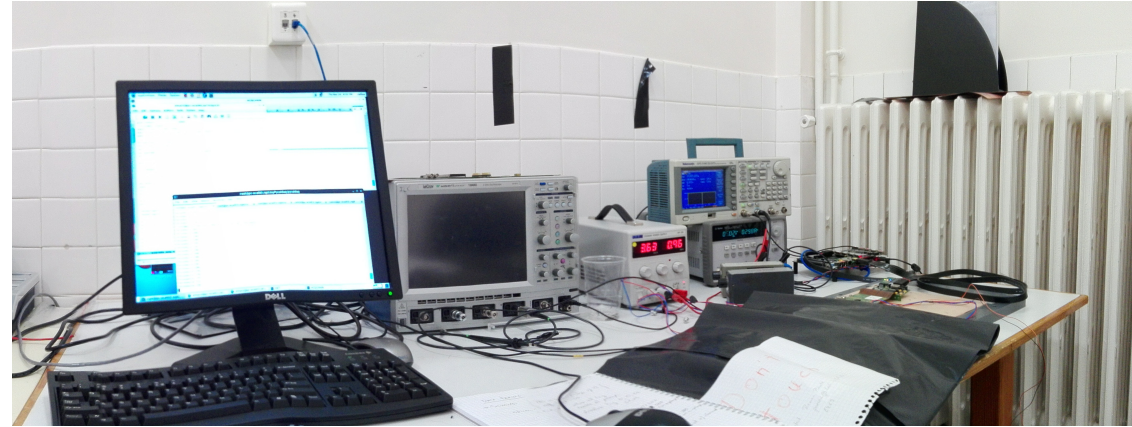
- Understanding of the BCID issue
- S-Curves or FindNoisy to define a first set of trigger thresholds
- Test and improve the setup with cosmics runs
- Integration of the other 5 layers into the stack

- We have booked two weeks at DESY, TB24/1
 - 12-25 June
 - http://particle-physics.desy.de/sites/site_particlephysics/content/e252106/e261123/infoboxContent275972/Testbeam_schedule2017v9_ger.pdf

- CERN beam test in September with SDHCAL ?

- Beam test readiness meeting by mid April ?
 - invite external reviewers as e.g. the Chair of the CALICE TB

- FEV8_COB module (only one)
 - 8 chips
- DAQ:
 - “old” LDA (link data agregator)
 - Outdated DAQ software
(calicoes 2.1-2)
- Main issues:
 - Intermittent usage → testbench not maintained



Power supplies

Spill signal generator

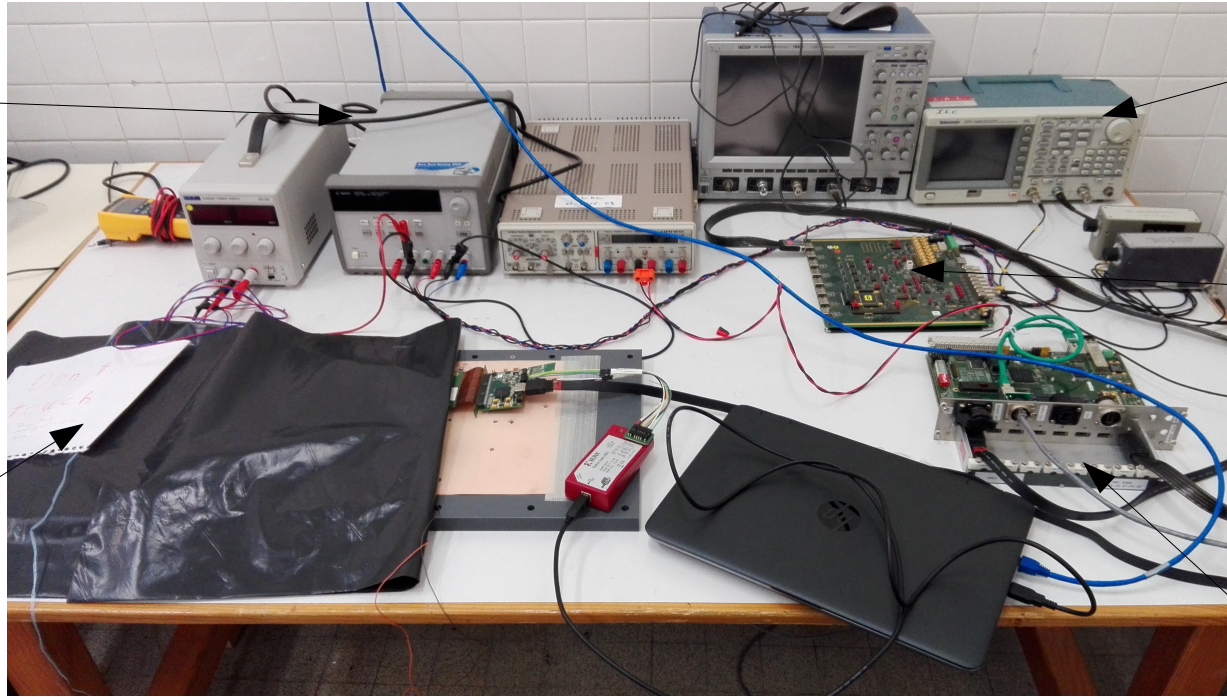
CCC:
Control clock card

GDCC
→ data concentrator

Hardware under test

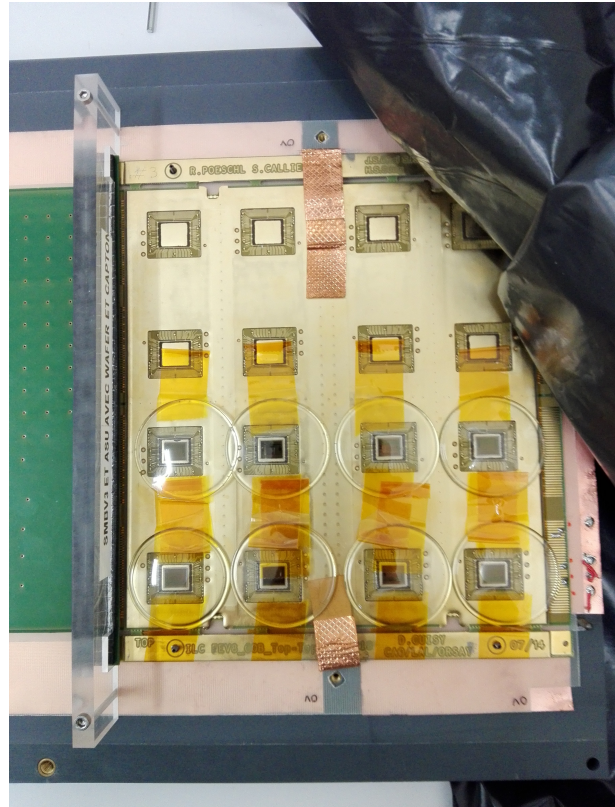
→ with high tech cover

PC
Connected
To the
GDCC

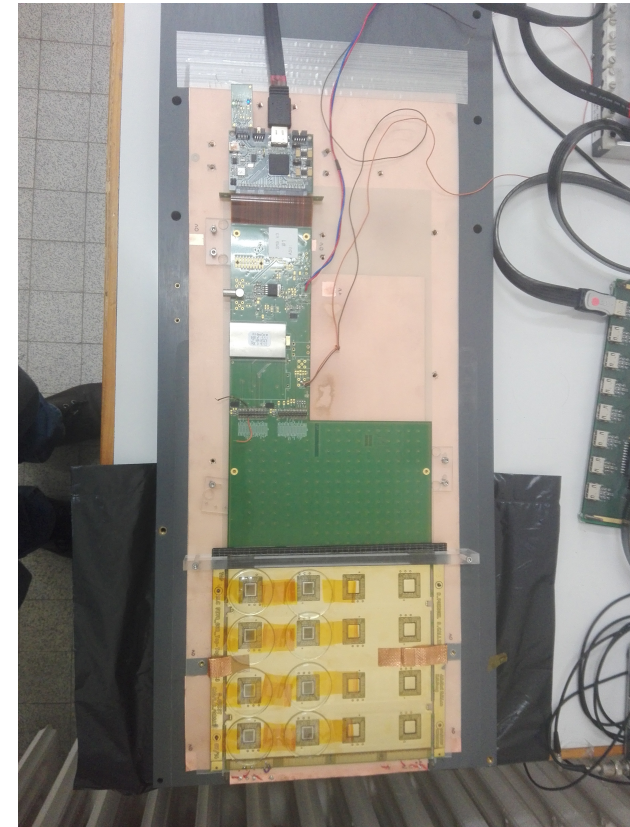


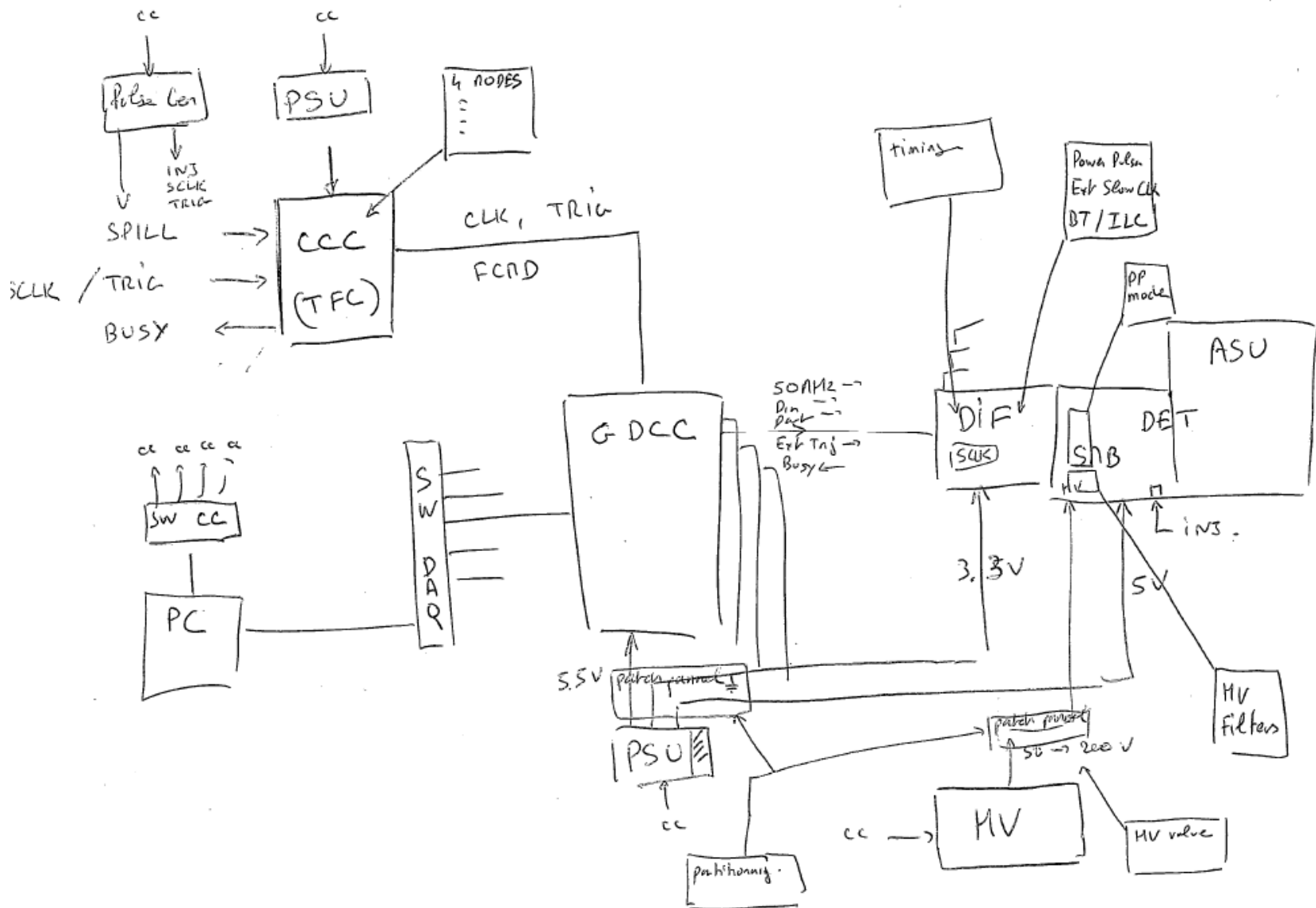


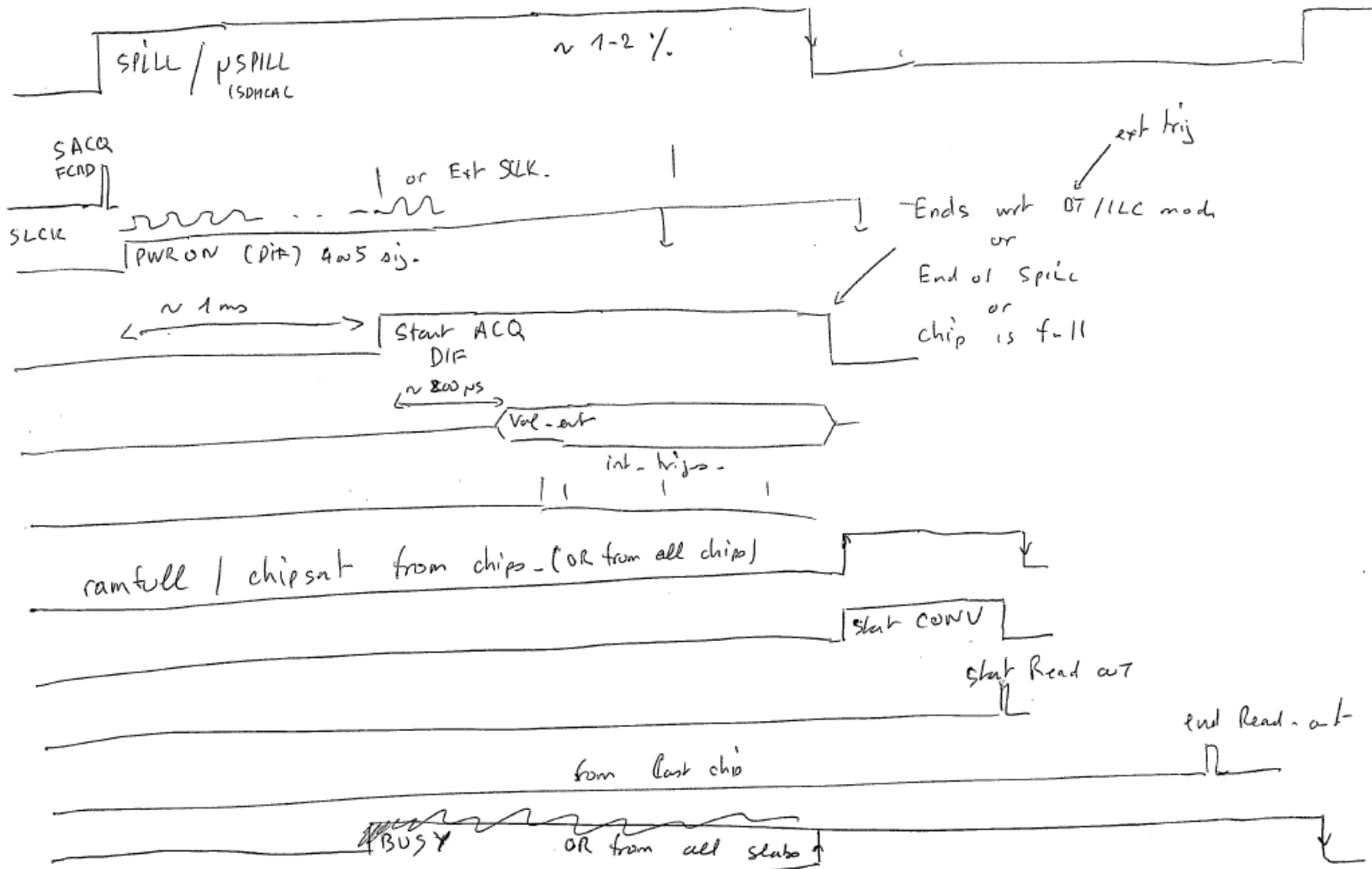
DIF: Detector card interface.
Sends configuration and control commands to the chips and gets the data of the chips and send them to the data concentrator.



FEV8_COB
Module with the chips and (in general) Si wafers







ext trig
 Ends wrt DT/ILC mode
 or
 End of Spill
 or
 chip is full